

## General Description

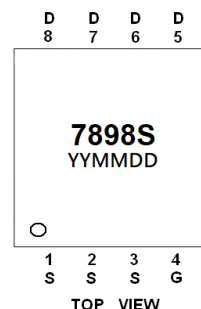
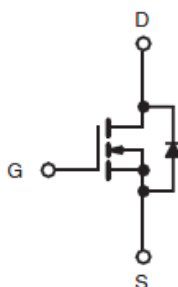
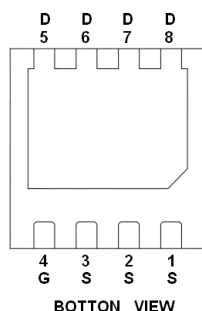
AFN7898S, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

## Features

- $I_D=7A, R_{DS(ON)}=105m\Omega@V_{GS}=10V$
- $I_D=7A, R_{DS(ON)}=115m\Omega@V_{GS}=7.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- DFN3X3-8L package design

## Pin Description ( DFN3X3-8L )



## Application

- Primary Side Switch
- Synchronous Rectification
- DC/DC Converters & DC/AC Inverters
- Boost Converters

## Pin Define

Pin	Symbol	Description
1~3	S	Source
4	G	Gate
5~8	D	Drain

## Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN7898SFN338RG	7898S	DFN3X3-8L	Tape & Reel	5000 EA

※ YY year code

※ MM month code

※ DD date code

※ AFN7898SFN338RG : 13" Tape & Reel ; Pb- Free ; Halogen -Free



### Absolute Maximum Ratings (T<sub>A</sub>=25°C Unless otherwise noted)

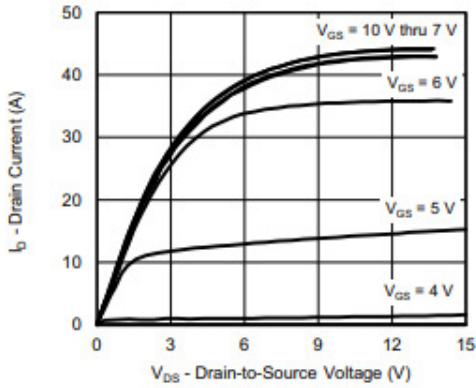
Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V <sub>DSS</sub>	200	V
Gate –Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current (T <sub>J</sub> =150°C)	T <sub>C</sub> =25°C	14	A
	T <sub>C</sub> =70°C	11	
Pulsed Drain Current ( t=100us )	T <sub>A</sub> =25°C	4.2	
	T <sub>A</sub> =70°C	3.2	
Continuous Source Current (Diode Conduction)	I <sub>S</sub>	14	4.2
Single pulse avalanche current	I <sub>AS</sub>	10	
Single pulse avalanche energy	E <sub>AS</sub>	5	mJ
Power Dissipation	T <sub>C</sub> =25°C	55	W
	T <sub>C</sub> =70°C	35	
Operating Junction Temperature	T <sub>A</sub> =25°C	4.8	°C
	T <sub>A</sub> =70°C	3.0	
Storage Temperature Range	T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Ambient	R <sub>θJA</sub>	21	°C/W
Maximum junction-to-case (drain)	R <sub>θJC</sub>	1.7	

### Electrical Characteristics (T<sub>A</sub>=25°C Unless otherwise noted)

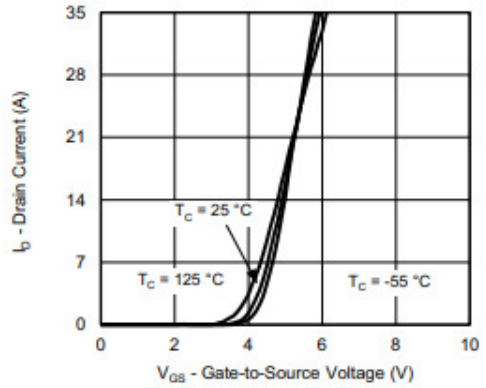
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	200			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	2		4	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =160V, V <sub>GS</sub> =0V			1	uA
		V <sub>DS</sub> =160V, V <sub>GS</sub> =0V T <sub>J</sub> =85°C			10	
On-State Drain Current	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ 5V, V <sub>GS</sub> =10V	15			A
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =7A		95	105	mΩ
		V <sub>GS</sub> =7.5V, I <sub>D</sub> =7A		100	115	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =7A		16		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =5.0A, V <sub>GS</sub> =0V		0.8	1.2	V
<b>Dynamic</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =7.5V I <sub>D</sub> ≡3A		9	15	nC
Gate-Source Charge	Q <sub>gs</sub>			3		
Gate-Drain Charge	Q <sub>gd</sub>			3		
Gate resistance	R <sub>g</sub>	f=1MHz	0.6	1.9	3.5	Ω
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V f=1MHz		715		pF
Output Capacitance	C <sub>oss</sub>			55		
Reverse Transfer Capacitance	C <sub>rss</sub>			8		
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> =100V, R <sub>L</sub> =33.3Ω I <sub>D</sub> ≡3A, V <sub>GEN</sub> =10V R <sub>G</sub> =1.0Ω		10	20	ns
	t <sub>r</sub>			15	30	
Turn-Off Time	t <sub>d(off)</sub>			15	30	
	t <sub>f</sub>			15	30	



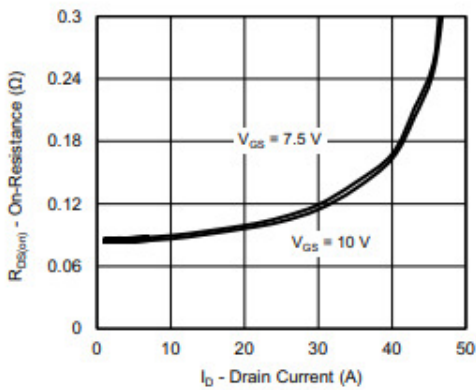
## Typical Characteristics



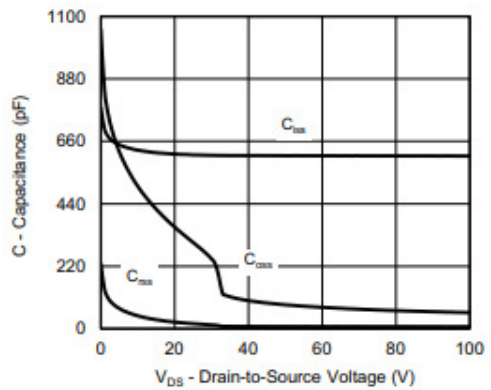
Output Characteristics



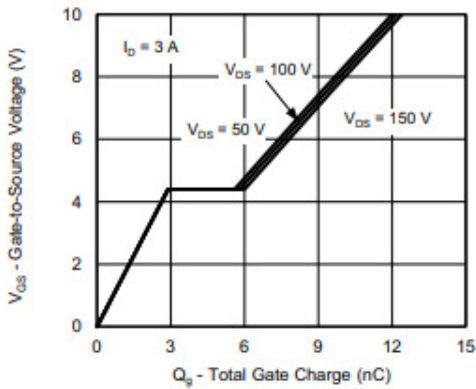
Transfer Characteristics



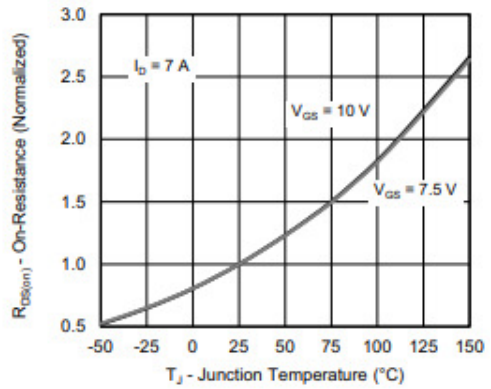
On-Resistance vs. Drain Current



Capacitance



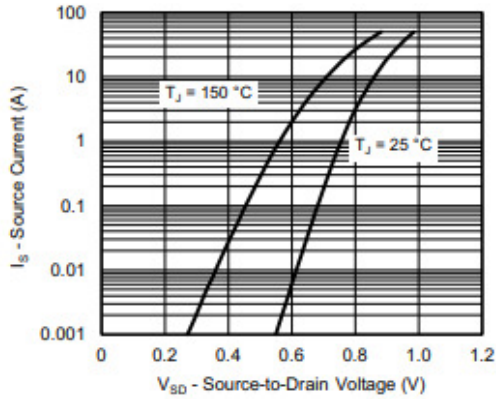
Gate Charge



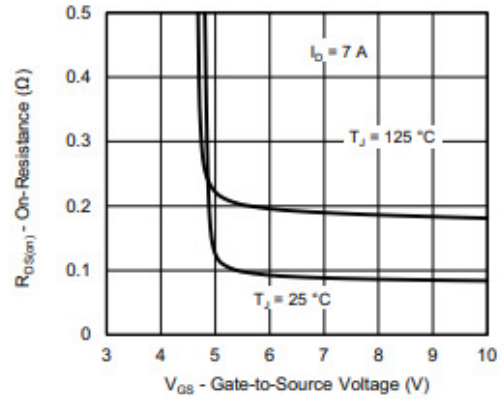
On-Resistance vs. Junction Temperature



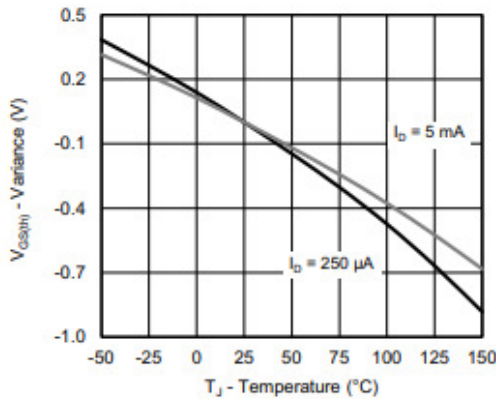
## Typical Characteristics



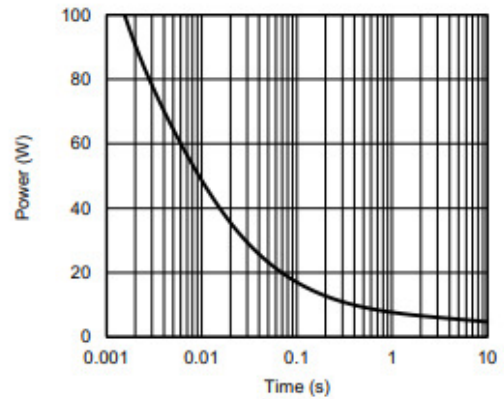
Source-Drain Diode Forward Voltage



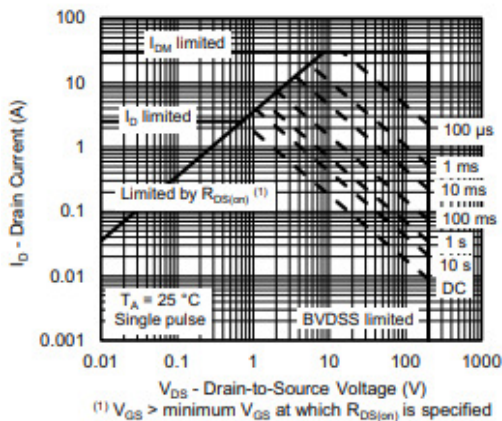
On-Resistance vs. Gate-to-Source Voltage



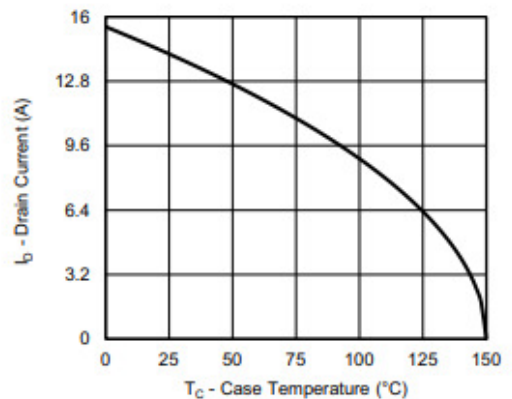
Threshold Voltage



Single Pulse Power, Junction-to-Ambient



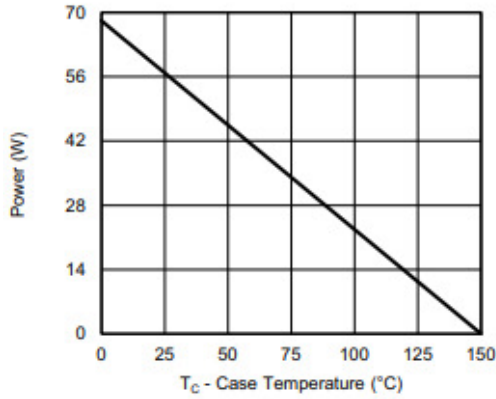
Safe Operating Area



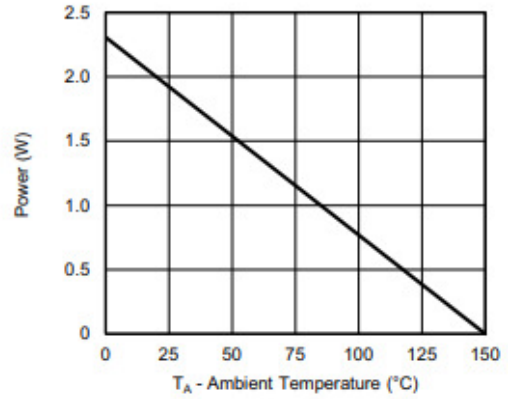
Current Derating <sup>a</sup>



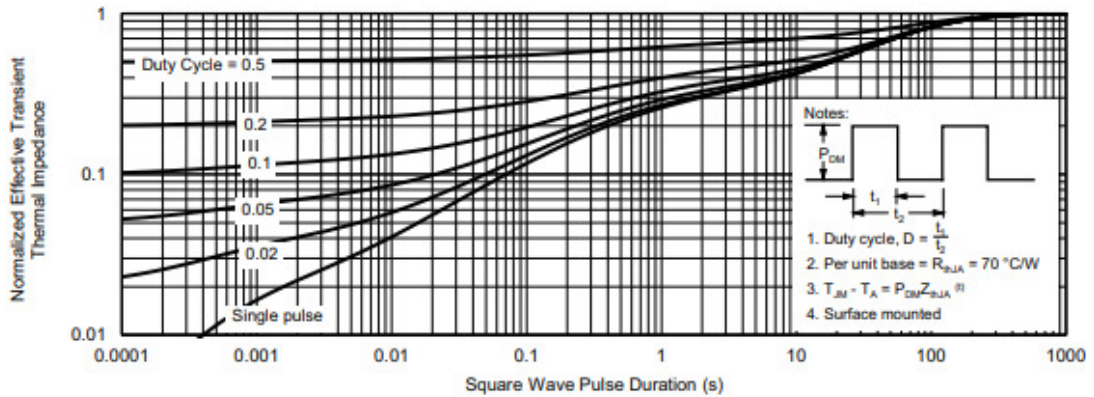
## Typical Characteristics



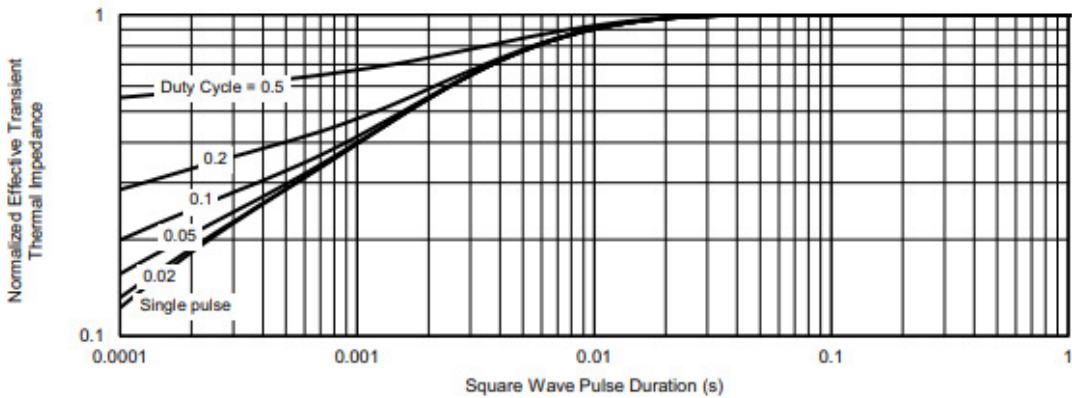
Power, Junction-to-Case



Power, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient

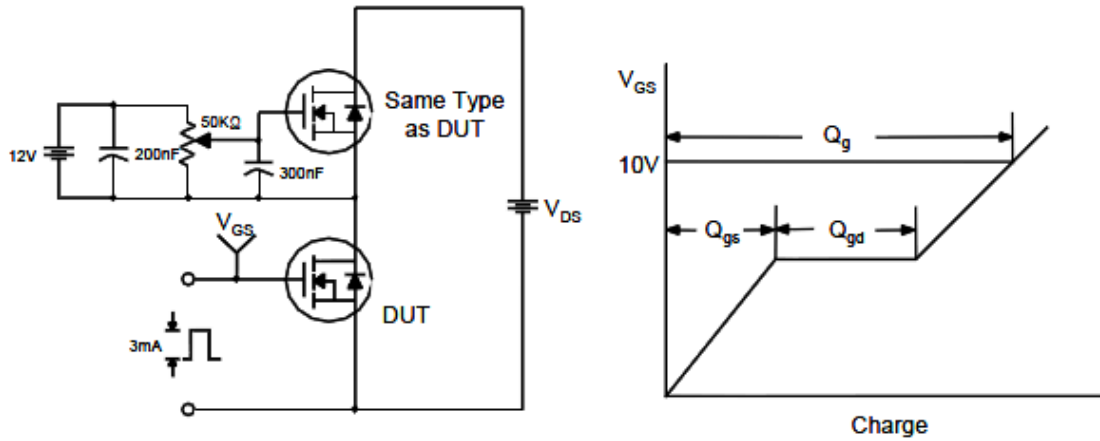


Normalized Thermal Transient Impedance, Junction-to-Case

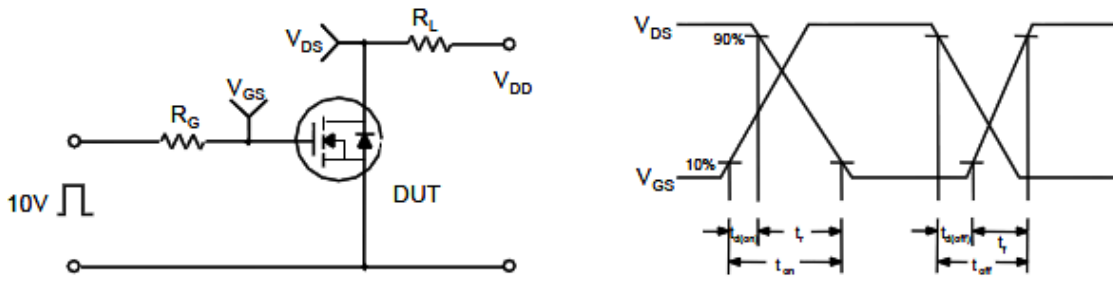


**Typical Characteristics**

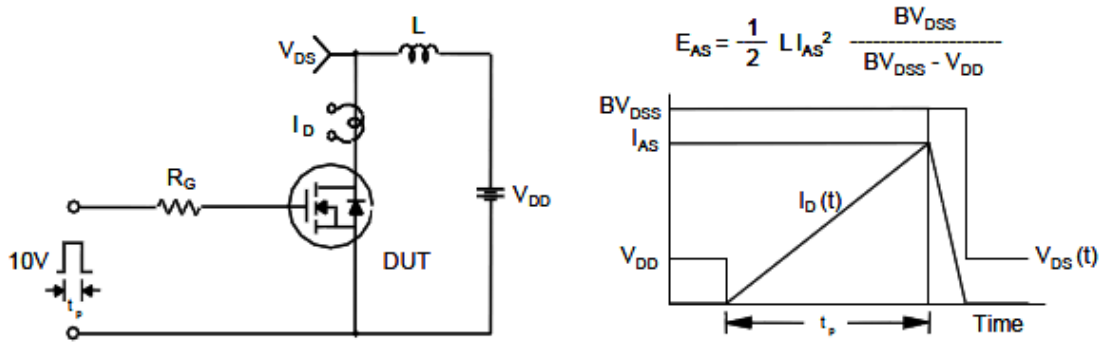
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

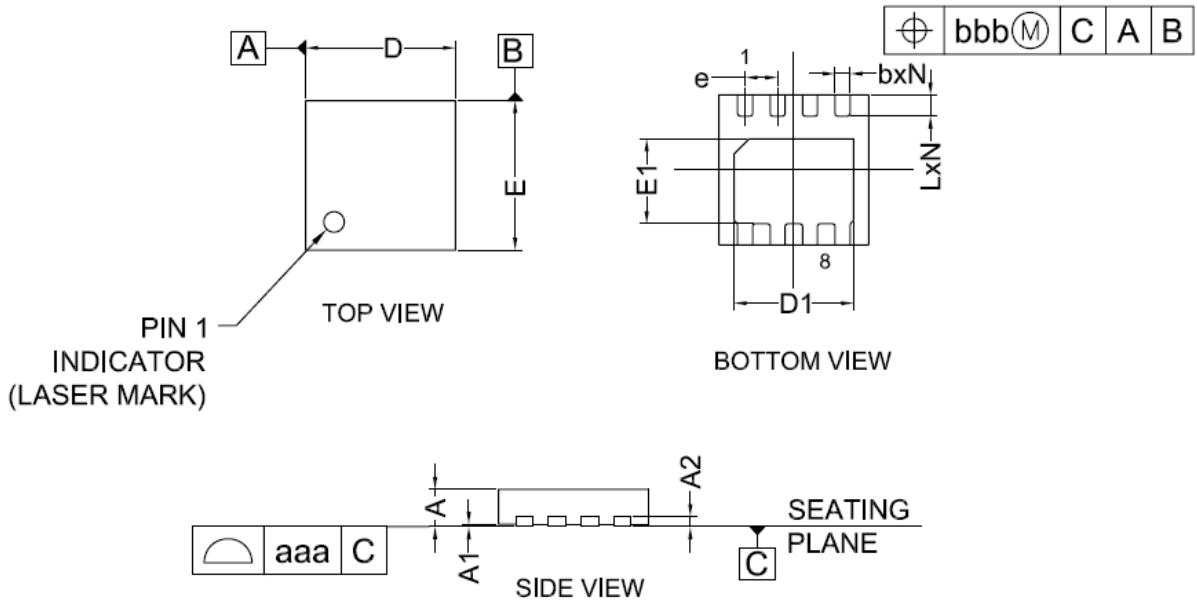


Unclamped Inductive Switching Test Circuit & Waveforms





**Package Information ( DFN3X3-8L )**



SYMBOL	MIN	TYP	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2	0.203		
b	0.25	0.30	0.35
D	2.90	3.00	3.10
D1	2.35	2.40	2.45
E	2.90	3.00	3.10
E1	1.65	1.70	1.75
e	0.65BSC		
L	0.37	0.42	0.47
N	8		
aaa	0.08		
bbb	0.10		

COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

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